**In the Specification:**

Please amend the paragraph at page 6, lines 6-14 as indicated below.

In one particular implementation, the present invention is used in connection with defect analysis and identification methods used to identify a defective resistive interconnect. Resistive interconnects are often developed as a result of a void in conductive material used for the interconnect. For an example manner in which to identify a resistive interconnect, reference may be made to U.S. Patent Application Serial No. 09/586,518 (AMDA.455PA/TT3843), entitled "Resistivity Analysis" and filed on June 6, 2000, which is incorporated herein by reference. In this example methodology, suspect circuitry in a semiconductor die is identified by using a state-changing operation of the circuitry to cause a failure due to the suspect circuitry. Using this state-changing operation, one of the circuit paths that electrically changes in response to heat is identified; a particular circuit portion therein is identified as being defective because it is resistive. Once a resistive interconnect is identified, the interconnect is accessed and imaged in a manner not inconsistent with the various example embodiments described herein.